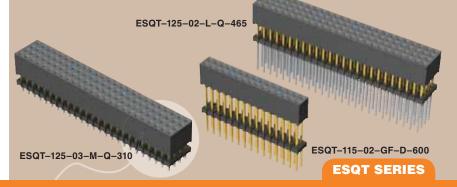




(2,00 mm) .0787"



FLEXIBLE ELEVATED SOCKET STRIPS

SPECIFICATIONS

For complete specifications see www.samtec.com?ESQT

Insulator Material:

Black Liquid Crystal Polymer Contact Material: Phosphor Bronze

Plating: Sn or Au over

50μ" (1,27 μm) Ni Current Rating (ESQT/TMMH):

4.5 A per pin (1 pin powered per row)

Operating Temp Range: -55°C to +125°C Contact Resistance: 10 mΩ

Insertion Depth: (2,62 mm) .103" to (5,03 mm) .198" with (0,38 mm) .015" wipe

Max Cycles:

100 with 10μ" (0,25 μm) Au Insertion Force: (Single contact only) 4 oz (1,11 N) avg. Withdrawal Force: (Single contact only) 3 oz (0,83 N) avg.

RoHS Compliant: Yes Lead-Free Solderable: Yes, for -S, -D & -Q (Wave only for -T, -5 & -6)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality





Other Solutions

Surface Mount See SQW and TLE Series.

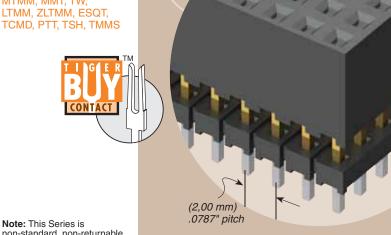


Low **Profile** See CLT Series.



Right Angle See SQW Series.

PC/104-Plus™ Sockets See ESQT-368 and PTHF Series. Mates with: TMMH, TMM MTMM, MMT, TW LTMM, ZLTMM, ESQT, TCMD, PTT, TSH, TMMS



High Retention Contacts

APPLICATION SPECIFIC OPTION: NOTEBOOK 2.5" DISK DRIVE INTERFACE

Call for part number.

non-standard, non-returnable

ESQT

LEAD PER ROW **STYLE**

PLATING OPTION

ROW **BODY OPTION** HEIGHT

OTHER OPTION

02 thru 50

No. of positions x

(2,00) .0787 + (0,30) .012

000000 10000000 (2,00) No. of

NO. PINS

Specify LEAD **STYLE** from chart

0787 rows

(6,35)

.250

(1,52)

(2,00)

.0787

Gold flash on contact, Matte Tin on tail = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

> – M = 20µ" (0,51 µm) Gold on contact, Matte Tin on tail –GF

= 15µ" (0,38 µm) Gold on contact, Gold flash on tail (Recommended for self-nesting) (-02 lead style only)

BODY

HEIGHT

-S = Single Row

-D = Double Row

-1 = Triple Row

-Q = Quad Row

> -5 = Five Row

-6= Six Row

TAIL

(1,27)

"XXX" = Body Height (in inches)

(7,87 mm) .310" minimum for -S, -D, -Q

(9,53 mm) .375" minimum for -T, -5, -6

"XXX" = Polarized Position (Indicate position

number)

OTHER SOLUTIONS



Paste In Hole (PIH) processing. Contact Samtec ASP Group. (Not recommended for stack through applications)

| LEAD | | MAX | MAX BODY |
|-------|---------|---------|----------|
| STYLE | | TAIL | HEIGHT |
| -02 | (21,59) | (13,72) | (20,32) |
| | .850 | .540 | .800 |
| -03 | (11,63) | (3,76) | (10,36) |
| | .458 | .148 | .408 |

.060 050 MIN → | - (0,50) .020 SQ - (2,00) .0787

> Due to technical progress, all designs, specifications and components are subject to change without notice. WWW.SAMTEC.COM